

- [1] THE DMD (ITEM 2) SHOULD BE ALIGNED TO DATUMS 'B' AND 'C' AS SHOWN IN VIEW A. THE FOAM ALIGNMENT SHIMS (ITEM 12) ARE TO BE INSERTED BETWEEN THE DMD EDGES AND THE OPTICAL INTERFACE AT THE APPROXIMATE LOCATIONS SHOWN. THE FUNCTION OF THE ELASTOMERIC WEDGES IS TO HOLD THE DMD AGAINST DATUMS 'B' AND 'C' AFTER IT HAS BEEN MANUALLY POSITIONED. THIS HOLDS THE DMD IN POSITION WHILE THE REMAINING ASSEMBLY IS COMPLETED
- [2] THE INSULATOR (ITEM 5) NEEDS TO BE OF SUFFICIENT THICKNESS TO ISOLATE THE PCB FROM THE METAL CLAMP (ITEM 6), TO KEEP IT FROM CAPACITIVELY COUPLING SIGNALS TOGETHER.
- [3] WHEN TIGHTENING SCREWS (ITEM 7) BE SURE CLAMPING FORCES DO NOT EXCEED THE MAXIMUM LOADS FOR THE THERMAL AND ELECTRICAL INTERFACE AREAS SPECIFIED IN THE DMD DATA SHEET. CARE SHOULD BE TAKEN AS THE SCREWS ARE TIGHTENED TO MAINTAIN A UNIFORM LOAD ACROSS THE AREAS.
- [4] CRITICAL GAP FOR COIL SPRING DESIGN TO CONTROL LOADS ON THE DMD ELECTRICAL INTERFACE AREA. THE SIZE OF THE GAP WILL VARY DEPENDING ON PART TOLERANCES AND SPRING PROPERTIES.
- [5] CRITICAL GAP FOR COIL SPRING DESIGN TO CONTROL LOADS ON THE DMD THERMAL INTERFACE AREA. THE SIZE OF THE GAP WILL VARY DEPENDING ON PART TOLERANCES AND SPRING PROPERTIES.



## Notes

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